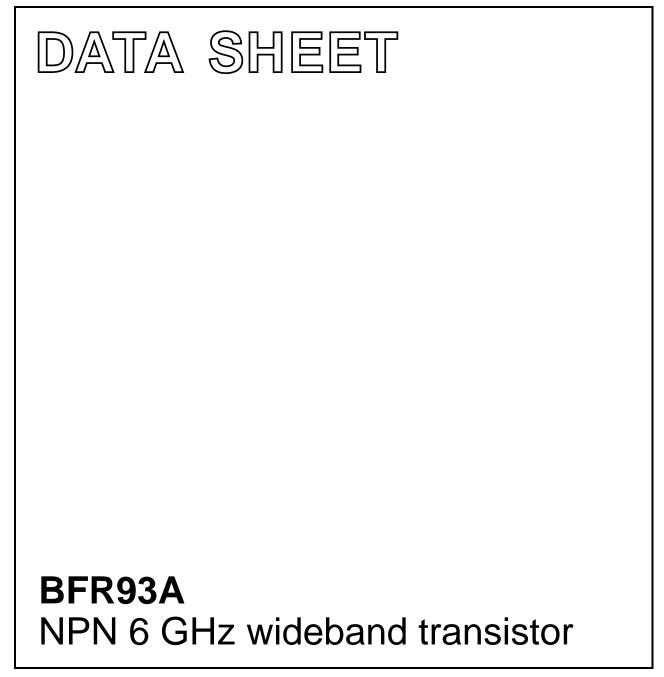
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of September 1995 1997 Oct 29



FEATURES

- High power gain
- Low noise figure
- Very low intermodulation distortion.

APPLICATIONS

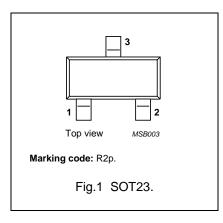
• RF wideband amplifiers and oscillators.

DESCRIPTION

NPN wideband transistor in a plastic SOT23 package. PNP complement: BFT93.

PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	15	V
V _{CEO}	collector-emitter voltage	open base	-	12	V
I _C	collector current (DC)		-	35	mA
P _{tot}	total power dissipation	$T_s \le 95 \ ^{\circ}C$	-	300	mW
C _{re}	feedback capacitance	I _C = 0; V _{CE} = 5 V; f = 1 MHz	0.6	-	pF
f _T	transition frequency	I _C = 30 mA; V _{CE} = 5 V; f = 500 MHz	6	-	GHz
G _{UM}	maximum unilateral power gain	I_{C} = 30 mA; V_{CE} = 8 V; f = 1 GHz; T_{amb} = 25 °C	13	-	dB
		$I_{C} = 30 \text{ mA}; V_{CE} = 8 \text{ V}; f = 2 \text{ GHz}; T_{amb} = 25 \text{ °C}$	7	_	dB
F	noise figure	I_{C} = 5 mA; V_{CE} = 8 V; f = 1 GHz; $\Gamma_{s} = \Gamma_{opt}$; T _{amb} = 25 °C	1.9	-	dB
Vo	output voltage		425	_	mV

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	15	V
V _{CEO}	collector-emitter voltage open base		-	12	V
V _{EBO}	emitter-base voltage	open collector	-	2	V
I _C	collector current (DC)		-	35	mA
P _{tot}	total power dissipation	$T_s \le 95 \text{ °C}; \text{ note } 1$	-	300	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	+175	°C

2

Note

1. T_s is the temperature at the soldering point of the collector pin.

Product specification

BFR93A

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R _{th j-s}	thermal resistance from junction to soldering point	$T_s \le 95 \ ^\circ C$; note 1	260	K/W	

Note

1. T_s is the temperature at the soldering point of the collector pin.

CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

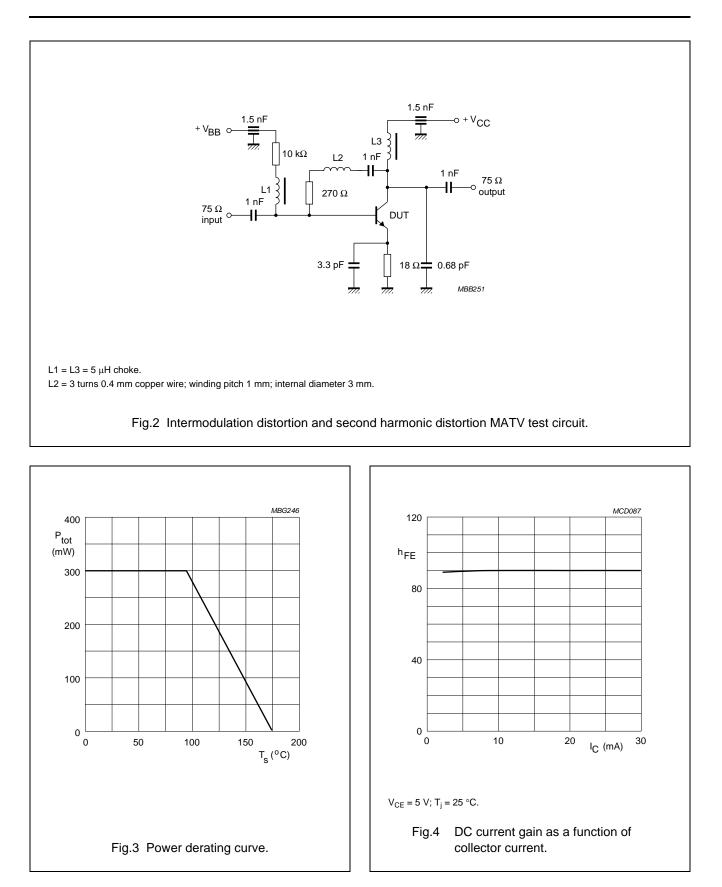
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = 5 V	-	-	50	nA
h _{FE}	DC current gain	I _C = 30 mA; V _{CE} = 5 V	40	90	_	
Cc	collector capacitance	I _E = i _e = 0; V _{CB} = 5 V; f = 1 MHz	_	0.7	_	pF
C _e	emitter capacitance	I _C = i _c = 0; V _{EB} = 0.5 V; f = 1 MHz	_	1.9	_	pF
C _{re}	feedback capacitance	$I_{C} = i_{c} = 0; V_{CE} = 5 V; f = 1 MHz;$ $T_{amb} = 25 °C$	-	0.6	-	pF
f _T	transition frequency	I _C = 30 mA; V _{CE} = 5 V; f = 500 MHz	4.5	6	-	GHz
G _{UM}	maximum unilateral power gain (note 1)	$I_C = 30 \text{ mA}; V_{CE} = 8 \text{ V}; f = 1 \text{ GHz};$ $T_{amb} = 25 \text{ °C}$	-	13	-	dB
		$I_C = 30 \text{ mA}; V_{CE} = 8 \text{ V}; f = 2 \text{ GHz};$ $T_{amb} = 25 \text{ °C}$	-	7	-	dB
F	noise figure (note 2)	$I_C = 5 \text{ mA}; V_{CE} = 8 \text{ V}; f = 1 \text{ GHz};$ $\Gamma_s = \Gamma_{opt}; T_{amb} = 25 \text{ °C}$	-	1.9	-	dB
		$I_C = 5 \text{ mA}; V_{CE} = 8 \text{ V}; f = 2 \text{ GHz};$ $\Gamma_s = \Gamma_{opt}; T_{amb} = 25 \text{ °C}$	-	3	-	dB
Vo	output voltage	notes 2 and 3	-	425	_	mV
d ₂	second order intermodulation distortion	notes 2 and 4	-	-50	_	dB

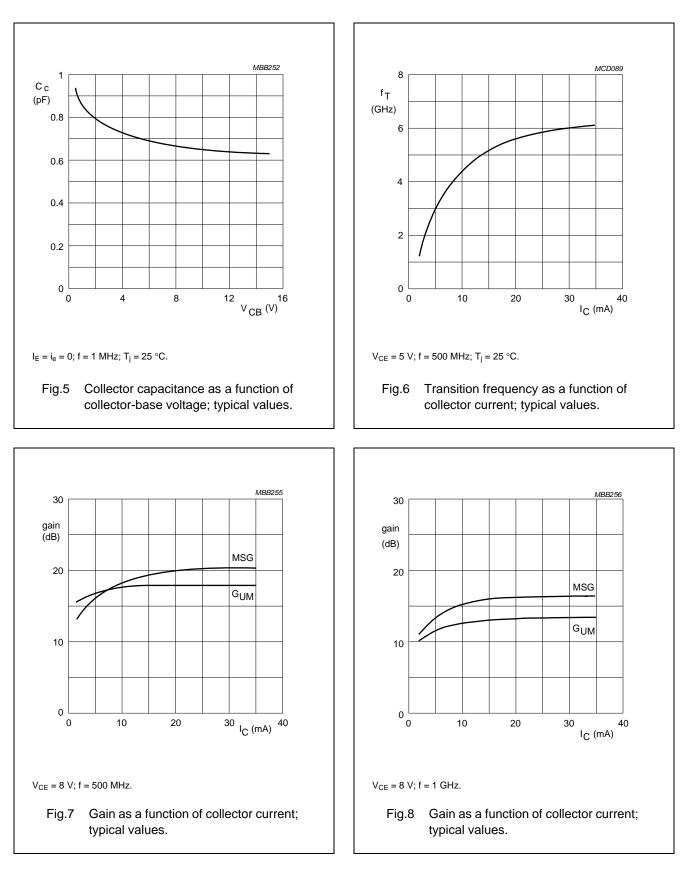
Notes

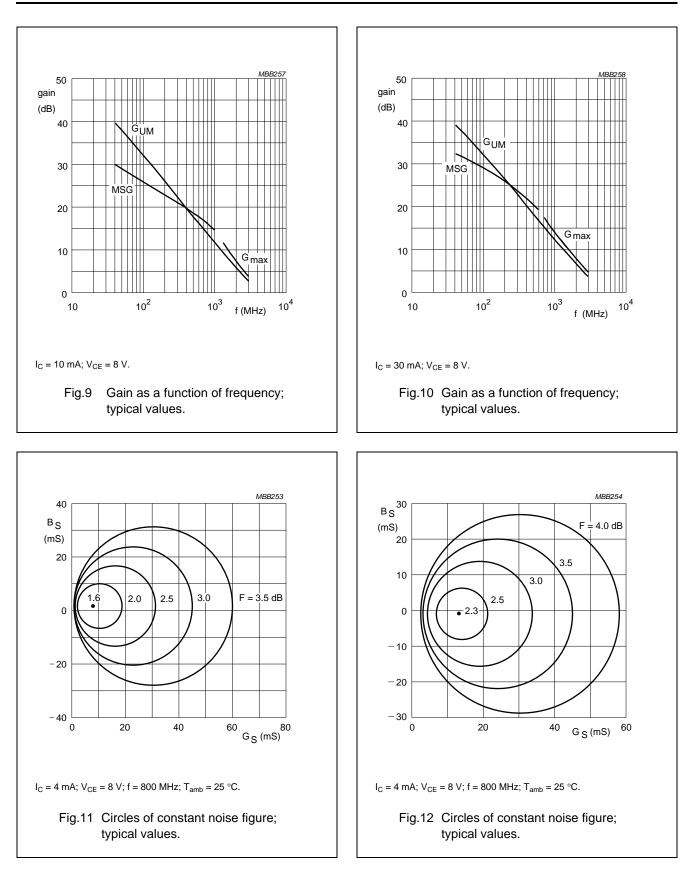
1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and $G_{UM} = 10 \log 10$

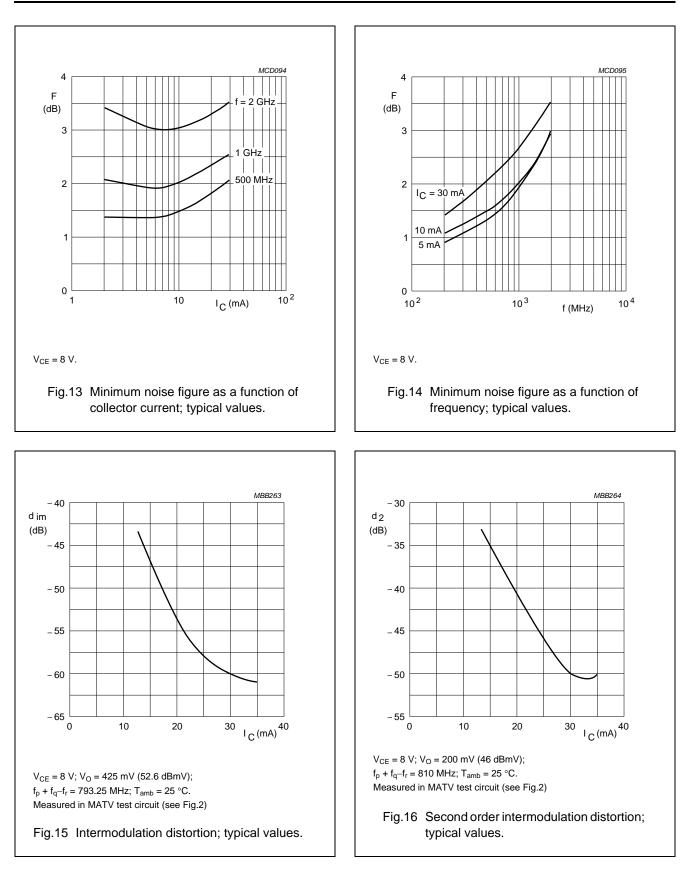
$$\frac{|S_{21}|^2}{(1-|S_{11}|^2)(1-|S_{22}|^2)}dB$$

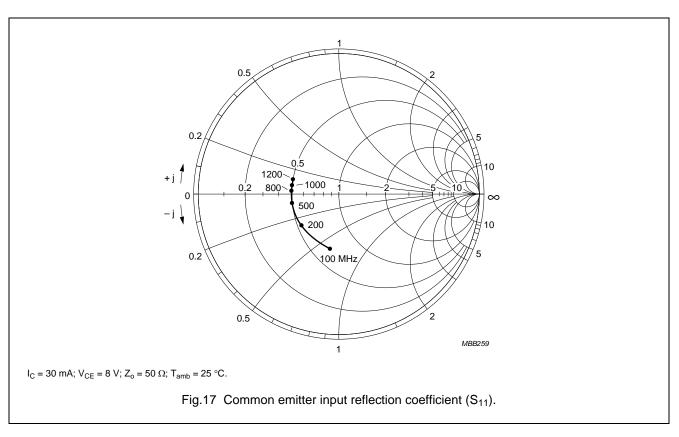
- 2. Measured on the same die in a SOT37 package (BFR91A).
- 3. $d_{im} = -60 \text{ dB} \text{ (DIN 45004B)}; I_C = 30 \text{ mA}; V_{CE} = 8 \text{ V}; R_L = 75 \Omega; T_{amb} = 25 \text{ °C};$ $V_p = V_O \text{ at } d_{im} = -60 \text{ dB}; f_p = 795.25 \text{ MHz};$ $V_q = V_O - 6 \text{ dB} \text{ at } f_q = 803.25 \text{ MHz};$ $V_r = V_O - 6 \text{ dB} \text{ at } f_r = 805.25 \text{ MHz};$ measured at $f_p + f_q - f_r = 793.25 \text{ MHz}.$
- 4. $I_{C} = 30 \text{ mA}; V_{CE} = 8 \text{ V}; R_{L} = 75 \Omega; T_{amb} = 25 \text{ °C};$ $V_{p} = 200 \text{ mV} \text{ at } f_{p} = 250 \text{ MHz};$ $V_{q} = 200 \text{ mV} \text{ at } f_{q} = 560 \text{ MHz};$ measured at $f_{p} + f_{q} = 810 \text{ MHz}.$

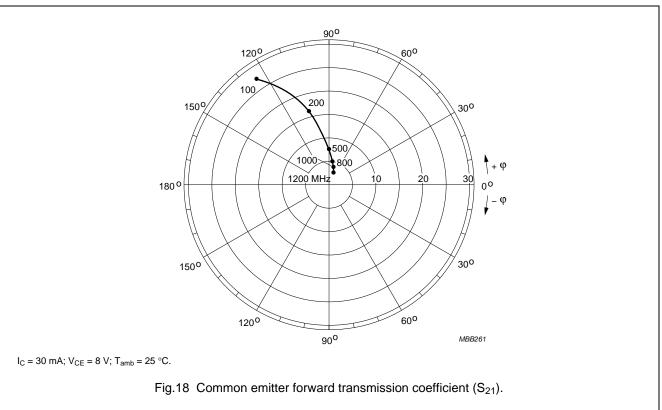


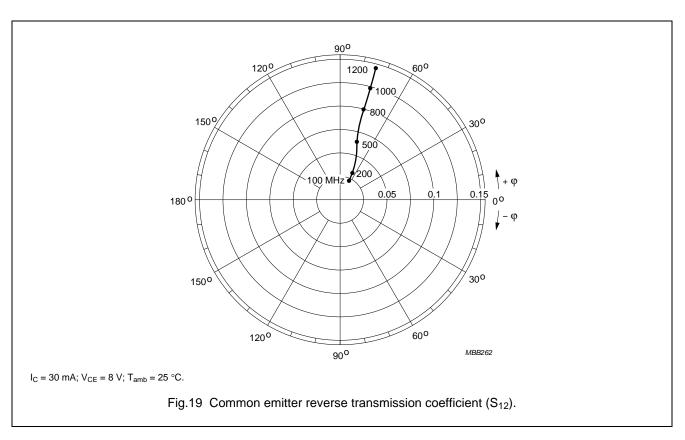


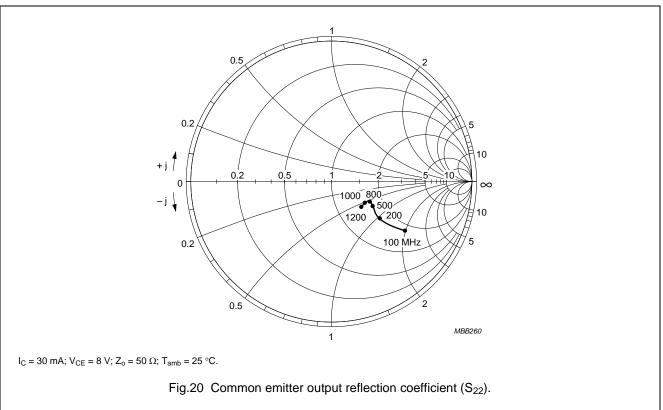




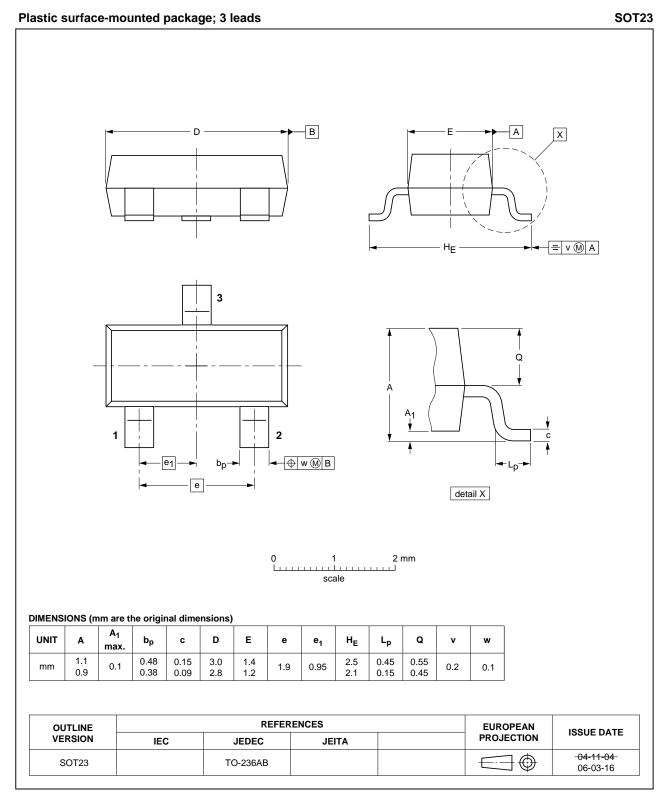








PACKAGE OUTLINE



BFR93A

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Contact information

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